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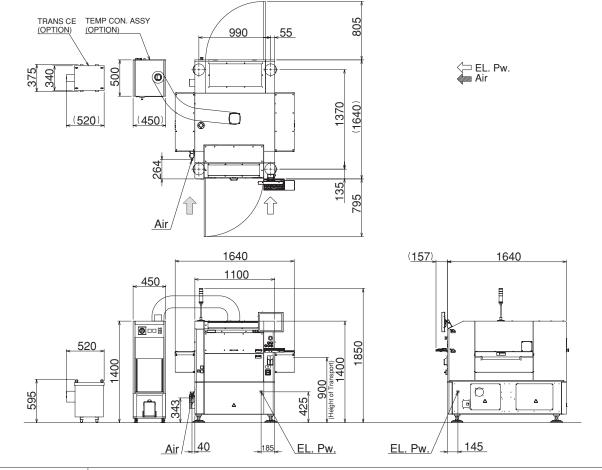
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11. Specifications

11.1 Major specifications

Outside	L1,640 x W1,640 x H 1,400 mm (Height and depth exclude projections, such as monitor, keyboard,		
dimensions	and signal tower, etc.)		
	L1,973× W1,640 × H1,400mm (carry-out side extension conveyor)		
Main body	Approx. 1,500 kg (with standard specifications)		
weight	Approx. 80 kg (air-conditioner)		
	Approx. 60 kg (overseas voltage transformer: for air-conditioner)		
Noise to be	78dB (A) or less		
produced			

- * The dimensions exclude any removable projection parts.
- * For details about detailed dimensions or dimensions with various options installed, see the figure below.
- * The following figure shows the machine with various options installed, such as air-conditioner.



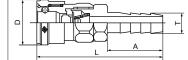
Air supply source

0.45 MPa or more (4.5 kgf/cm² or more), clean and dry air

* Supply the air with excellent quality that has passed through the air dryer and air filter on the line side of the air supply source. (The air filter built-into this machine is intended to protect the machine. To maintain the function and performance of this machine at their optimal levels for an extended period of time, it is necessary to keep the clean and dry status on the line side of the customer's air supply source.)

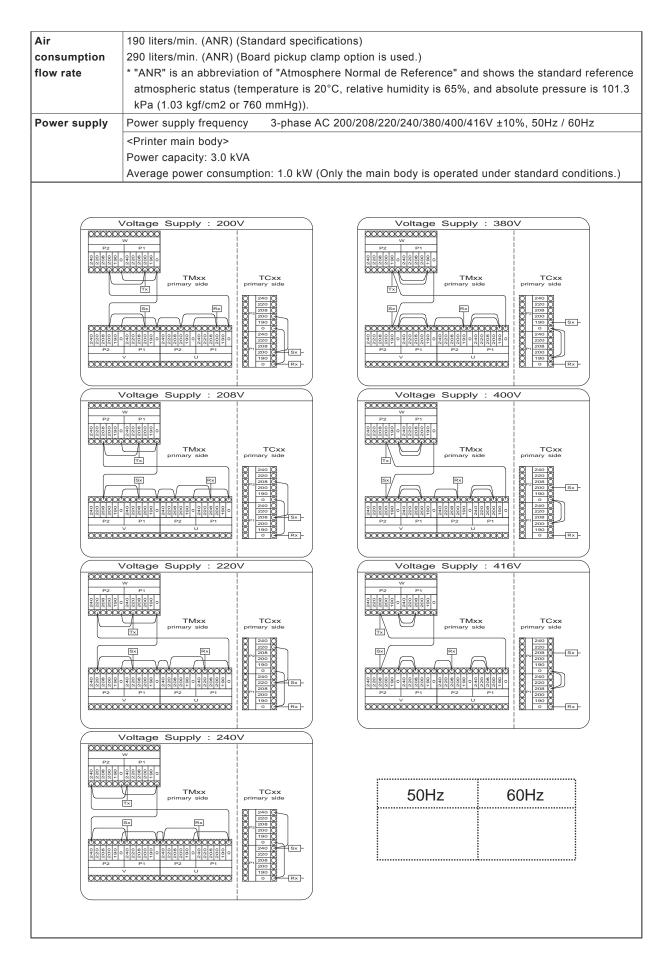
Air connection coupler (Attached to the main body)

NITTO's HI coupler 30SH socket side



D: \$\phi26.5 mm, T: \$\phi11.3 mm, L:76.5 mm, A:34 mm

* To maintain a sufficient air flow rate, use 3/8-inch air hose (inside diameter is Φ8 mm or more).



Power supply connection	Power supply cable	Conductor cross-sectional area is 3.5 mm ² or more.	
	securely before con * Connect the main be	Insulation sheathed crimp terminal L2 (2) L3 (3) W Crimp round terminal Chock accident, make sure that the main power supply is shut down enecting the power supply. Dody grounding cable securely. The eneeds another power supply that is separated from the printer	
Environmental conditions	main body. Temperature	Function assurance: 15 to 30°C Accuracy assurance: 20 to 28°C Recommended operating temperature: 23 to 26°C	
	Humidity	Function assurance: 20 to 80% (No dew condensation allowed.) Recommended operating humidity: 40 to 60% * Keep a humidity of approx. 40% or more as static electricity prevention measures. * When using an industrial humidifier, use water equivalent to DI water.	
	Atmosphere There shall be no dirt and dust. There shall be no organic solvent vapor, sulfurous acid gas, chlorine gas, and flammable gas.		
	Altitude 1,000 m or less above sea level * This avoids that the air pressure or cosmic ray adversely affect the insulation performance.		
	Installation floor status	The floor withstanding load capacity shall be approx. 500 kg/m². * For the floor withstanding load capacity, consult the specialists who know the installation place well with the information on equipment weight, floor sharing area, and adjuster foot positions. * The floor shall be flat and have sufficient strength so that it does not vibrate during operation. The floor shall have the concrete strength or its equivalent. In particular, wooden floor, office floor, and grating are not allowed to use. * If the floor is not concrete, consult the specialists who know the installation place well and construct the reinforcement work for the portions where the equipment feet are placed.	
	Ambient noise There shall be no significant noise. Equipment operation sound and alarm sound can be heard without fail.		
	Ambient light Immunity/Electro magnetic resistance or electro magnetic susceptibility	Strong light, such as sunlight does not enter the vision system. See "10.5 CE marking".	
	Emission/electro magnetic noise production or electro magnetic noninterference	See "10.5 CE marking".	

	ı				
Board transport speed		50 to 550 mm/sec.: 50Hz/60Hz			
		(Transport speed settings at shipment, Low-speed: 200 mm/ sec., High-speed: 400 mm/sec.)			
Drinting conchility		* The transport speed may vary depending on the board weight, etc.			
Printing capability		11.0 sec./cycle	nal conditions: L 180 x W 130 board size, squeegee speed 100 m/sec.,		
			mm, over-stroke 10 mm, board hold flap is used., board separation		
		•	board separation speed 2 mm/sec., cleaning work is not performed.		
		distance 2 mm, board separation speed 2 mm/sec., cleaning work is not performed.			
		To verify the print	ting capability with the customer's board, mask, and solder paste, the		
		separate evaluation experiment is needed. For details, contact YAMAHA.			
Printing accuracy (YAMA	HA's	Printing accuracy	(3s): ± 0.025 mm		
evaluation test board, sta	andard	Position repeatab	oility (3s): ± 0.005 mm		
mask, and standard sold	er paste				
are used.)					
Signal tower color	TYPE A	TYPE B	TYPE A is YAMAHA's standard specifications while TYPE B is often		
specifications			used in the EU area.		
	Red lamp	While lamp	Emergency stop status (emergency stop button or safety cover		
			switch is activated.)		
	Yellow lam	p Blue lamp	Stop status due to error stop (recognition error or board clamp		
			error, etc.) or interlock.		
	Green lamp	Green lamp	Automatic operation is running.		
Operation panel button TYPE A		TYPE B	TYPE A is YAMAHA's standard specifications while TYPE B is often		
color specifications			used in the EU area.		
	White	White READY (Emergency stop status or servo ON)			
	White	White RESET (Data reset)			
	Green	Green	START (Automatic operation start)		
	Red	White	STOP (Automatic operation stop)		
Yellow		Blue	ERROR CLEAR (Error lock status cancellation)		
Languages used on			glish, Chinese, and Korean.		
display screens and in		red selections using [B00092] Display language and [B00098] Language written in			
manuals		"1. Machine configuration".			
			nt in an EU country, see "10.5 CE marking".		
Entry data	100MB/ma				
	Data entry method: Data entry unit supplied with the machine main unit				
Minimum positioning	X-axis/Y-axis/Z-axis: 0.001 mm				
resolution settings R-axis: 0.0					
Mask and board	X: ±6.4 mm				
correction ranges X: ±6.4 m		ı			
Jon Jon Janges	R: ±1.0°				
External interface	LAN 1 port (See "7.8 Network" and "7.9 Anti-virus measures".)				
Internal memory	Built-in 1GB Flash Card * 1 pc.				

* For storage of files, such as OS, printer application software, board data, mask data, squeegee

data, vision data, machine information, and production history information, etc.

USB flash memory with a capacity of 1GB or more * 1 pc. (Supplied as standard accessory.: For data backup) **Board transport height** 900 mm ± 10 mm (From the floor level to the top surface of the transport belt.)

External memory

11.2 Printing section (3S head)

11.2.1 Printing section

Item	Specifications		
Printing application pressure (printing pressure) producing system	AC servomotor + compression spring drive		
Printing pressure control method	Load cell sensor is built-into the application pressure producing system to construct the feedback control circuit.		
Printing pressure setting range	Setting range: 5 to 200N Control accuracy: In a range of 5 to 100N, ±2N (feedback control) In a range of 100 to 200N, ±2% (feedback control)		
Squeegee printing direction	Direction perpendicular to the board transport direction (conveyor width direction)		
Squeegee printing speed setting range	Setting range: 2 to 200 mm/sec.		
Squeegee up/down drive system	AC servomotor * Doubles as printing application pressure (printing pressure) producing system. Solder drip prevention effect can be expected using the deceleration setting of the up/down speed.		
Relationship between squeegee and mask	Mask surface follow-up effect to support one point of the squeegee center in the horizontal direction is produced (floating in the rotation direction).		
Board separation process pattern	to steps/program The board separation speed and board separation distance shown below are combined to sequentially execute up to ten steps.		
Board separation distance setting	Setting range 0.01 to 5.00 mm Control unit 0.01 mm		
Board separation speed setting	Setting range 0.01 to 20.00 mm/sec. Control unit 0.01 mm/sec.		

11.2.2 3S head

Item			Specifications		
Squeegee configuration		One squeegee co	One squeegee configuration		
		* Both ends (blade	* Both ends (blade parts) of one dedicated squeegee are used in		
		the forward and	backward squeegee p	rinting directions.	
		* Easy cleaning w	ork and reduction of w	aste solder are expected.	
Attack angle		Variable change f	rom 45° to 65°		
		* It is expected to	* It is expected to set optimal conditions and improve the filling		
			ability according to the viscosity and thixotropy of the solder.		
Squeegee		Metal squeegee o	r urethane squeegee (hardness 90)	
Settable rolling	Attack angle	45°	55°	65°	
stroke (*)	Board width is	50mm or less	50mm or less	50mm or less	
	440mm or less.				
	Board width is	50mm or less	46mm or less	40mm or less	
460mm.					
Over stroke	,	5 to 15mm	'		

^{*} If the board width exceeds 440mm, the settable rolling stroke may vary depending on the attack angle.

^{*} For details about double squeegee head (option), see "12.8.2 Double squeegee head".

11.2.3. 3S head - Additional set

12 kinds of squeegee and holder sets for the 3S head installed in the machine at shipment from the factory are provided. Select a desired squeegee and holder set using [B00004] Squeegee & holder set installed at shipment in "1 Machine configuration".

* Only one squeegee & holder set is installed in the 3S head.

The metal squeegee is equipped with the cover that protects the blade separated from the 3S head. Squeegee & holder sets with different materials and lengths can be additionally arranged as spare parts for the 3S head to be included in the machine.

Set additional options using [B00501] to [B00556] Spare squeegee & holder set in "3. Arrangements/ -1-Squeegee & holder".

Squeegee length	Metal squeegee & holder set	Urethane squeegee & holder set
530mm	"KHT-M71A0-00X, Metal Assy 3S 530" B00004 B00501 530	"KHT-M71B0-00X, Urethane Assy 3S 530" B00004 B00551 530
440mm	"KHT-M71A0-10X, Metal Assy 3S 440" B00004 B00502 440	"KHT-M71B0-10X, Urethane Assy 3S 440" B00004 B00552 440
400mm	"KHT-M71A0-20X, Metal Assy 3S 400" B00004 B00503 400	"KHT-M71B0-20X, Urethane Assy 3S 400" B00004 B00553 400
350mm	"KHT-M71A0-30X, Metal Assy 3S 350" B00004 B00504 350	"KHT-M71B0-30X, Urethane Assy 3S 350" B00004 B00554 350
300mm	"KHT-M71A0-40X, Metal Assy 3S 300" B00004 B00505 300	"KHT-M71B0-40X, Urethane Assy 3S 300" B00004 B00555
250mm	"KHT-M71A0-50X, Metal Assy 3S 250" B00004 B00506 250	"KHT-M71B0-50X, Urethane Assy 3S 250" B00004 B00556 250

11.2.4 3S head - Additional squeegee

18 kinds of replacement squeegee single units (excluding the holder) for the 3S head are provided. Set additional options using [B00511] to [B00566] Spare squeegee single unit in "3. Arrangements/ -1- Squeegee & holder".

3S metal normal blade single unit

Reference No.	Class	Size/Part No., Part name	
B00511	530mm	530 A A A A A A A A A A A A A A A A A A A	KHT-M71AA-A0X, Metal SQG Weld 3S 530
B00512	440mm	440 Report to the second of th	KGY-M71EA-A0X, Metal SQG Weld 3S 440
B00513	400mm	400	KGY-M71DA-A0X, Metal SQG Weld 3S 400
B00514	350mm	350 a	KGY-M71CA-A0X, Metal SQG Weld 3S 350
B00515	300mm	300 a	KGY-M71BA-A0X, Metal SQG Weld 3S 300
B00516	250mm	<u>250</u> → #	KGY-M71AA-A0X, Metal SQG Weld 3S 250

3S metal thin plate blade single unit for half-etching mask

Reference No.	Class	Size/Part No., Part name	
B00521	530mm	530 PROFESSION PROFESS	KHT-M71AA-B0X, Metal SQG(S) Weld 3S 530
B00522	440mm	440 = 440 =	KGY-M71EA-B0X, Metal SQG(S) Weld 3S 440
B00523	400mm	400	KGY-M71DA-B0X, Metal SQG(S) Weld 3S 400
B00524	350mm	350	KGY-M71CA-B0X, Metal SQG(S) Weld 3S 350
B00525	300mm	300	KGY-M71BA-B0X, Metal SQG(S) Weld 3S 300
B00526	250mm	250 A B B B B B B B B B B B B B B B B B B	KGY-M71AA-B0X, Metal SQG(S) Weld 3S 250

3S urethane squeegee single unit

Reference No.	Class	Size/Part No., Part name	
B00561	530mm	530 30	KHT-M71BB-00X,
B00301	55011111		Urethane SQG 3S 530
B00562	4.40mm	44030	KGY-M71K3-A0X,
B00362	440mm		Urethane SQG 3S 440
B00563	400mm	40030	KGY-M71J3-A0X,
B00563	40011111		Urethane SQG 3S 400
B00564	350mm	35030,	KGY-M71H3-A0X,
B00304	35011111		Urethane SQG 3S 350
B00565	300mm	300 30,	KGY-M71G3-A0X,
B00303	30011111		Urethane SQG 3S 300
DOOFEE	250mm	25030	KGY-M71F3-A0X,
B00566	250mm		Urethane SQG 3S 250

11.3 Mark recognition section

The machine is equipped with a vision camera system shown in the table below to recognize the board mark and mask mark, and inspect the printed solder paste.

Make desired selections using [B00012] Board FID mark vision camera, [B00013] Print mask vision camera, [B00011] Print inspection camera in "1. Machine configuration".

11.3.1 Board vision camera (CCD camera unit for board mark recognition)

Item	Remarks		
System	Board FID mark vision camera (standard) * FID: An abbreviation of fiducial		
Layout area CX-axis above conveyor			
Field-of-view	5mm x 5mm		
Application	Fiducial mark detection, bad mark detection, and teaching		
 Circle Φ 0.5 to 2 mm (YAMAHA's recommendation), Square Φ 0.5 to 2 mm, to 2 mm The difference between the bright and dark portions on the mark side and board side shall be sufficient. (The contrast shall be clear.) There shall be no scratch on the mark surface. It is accepted that the light reflector is located on either the mark side or be the shall be no resist, silk print, and other pattern with optical property smark in an area with a width of 0.2 mm from the outer periphery of the mashape or frame shape). A shape to be scanned shall be unique within the state of the shape of the			
Mark surface	Copper foil, gold plating, solder leveler (plating)		
Background material	Glass fiber reinforced epoxy resin board is optimal. * For ceramic or polyimide (flexible boards), the verification test is needed.		
Detection area Enter numeric values within the field-of-view range to set a detection area. (waste image processing time.)			
Mark layout	2 points or 4 points on board (It is preferable that the marks are located on the diagonal line.)		

11.3.2 Mask vision camera (CCD camera unit for mask mark recognition)

Item	Remarks					
System	Mask mark vision camera (standard)					
Layout area	Side surface of main stopper, MS-axis					
Field-of-view	Approx. 10 mm x 7.5 mm					
Application	Mask mark detection (Marks created on the back side of the mask are detected.)					
Mark specifications	Marks are formed so that images can be detected on the board contact side of the mask (back side and top side). Squeegee slide surface of mask Board contact surface of mask Non-through hole (half-etching concave part) Black resin filling type Through hole (paste application area) The difference between the bright and dark portions on the mark and mask surface shall be sufficient. (The contrast shall be clear.) It is preferable that the mark is the black resin (carbon) filling or through hole (* outside of the solder paste application area). It is accepted that the bright and dark portions on the mark and mask surface are reversed. When the raw material of the mask is resin or mesh woven fabric, the optical transparency shall be checked carefully. Circle Φ 0.5 to 2 mm (YAMAHA's recommendation), Square Φ 0.5 to 2 mm, Rhombus Φ 0.5 to 2 mm There shall be no scratch and contamination on the mark surface. There shall be no pattern with optical property similar to the mark in an area with a width of 0.2 mm from the outer periphery of the mark (doughnut shape or frame shape). The mark shape shall be unique in the field-of-view.					
Mark position	Back side of mask (Board surface side) 2 points or 4 points in a range of X: Mask center ± 255 and Y: Mask center ± 230. * It is preferable that the mask mark position corresponds to the board recognition mark.					

^{*} For details about print inspection camera, see "12.3 Print inspection camera specifications".

11.4 Cleaning system

This cleaning system is intended to automatically clean the board contact surfaces (back side and top side) of the mask after mask separation. (The manual cleaning is also possible.)

Fine solder paste residue is removed through the wiping with the non-woven fabric and suction cleaning with the blower.

The wet or dry wiping can be selected and the speed and the number of repetition cycles can also be set. According to the board print cycles and elapsed time, the cleaning process program is executed intermittently.

Set an applicable length (board length in the conveyor transport direction or width of cleaning non-woven fabric) of the cleaning system at shipment from the factory using [B0052] Cleaner head & non-woven fabric roll in "1 Machine configuration".

Ite	em	Specifications					
System		Cleaning in cooperation between dry/wet non-woven fabric wiping and blower suction					
Intermittent operation setting control * Print count setting * Print count setting Elapsed time setting elapsed time setting can be used together.		 Cleaning is performed at intervals of printed boards set in the program. Cleaning method: Auto/Manual/Auto and Manual are used together. Automatic cleaning mode: Wet/dry/Wet and Wet are used together. Cleaning is performed when the elapsed time reaches the machine stop time or standby time set in the program. Cleaning method: Auto/Manual Automatic cleaning mode: Wet/Dry 					
Cleaning non-wo	ven fabric	 Width of non-woven fabric: 530 mm/440 mm/360 mm/260 mm Outside diameter of roll: Approx. φ 90 mm (Approx. 30 mm roll) Core paper tube: Inside diameter, φ 25.4 mm, Paper thickness, 2 mm Set desired items using [B00052] Cleaner head & non-woven fabric roll and [B00296 to B00299] BEMCOT paper roll for cleaning (spare) in "1. Machine configuration". * Be sure to use the cleaning non-woven fabric specified by YAMAHA that is set as described above. If other non-woven fabric is used, this may cause insufficient cleaning effect or malfunction. In particular, if the cleaning head specifications do not meet the width, serious trouble may occur in the machine unit. 					
Solvent tank Solvent designat	ion	Ethyl alcohol or isopropyl alcohol CAUTION: Use of solvent other than that shown above may cause, • Higher toxicity for human body. • Stronger flammability. • Damage to equipment part, electric circuit, or other plastic tube, or promotion of deterioration. In the worst case, fire may occur. So, do not use other solvent. Particularly, never use acetone.					
Dry wiping		Forward movement speed setting: 1 to 225 m/sec. Backward movement speed setting: 1 to 225 m/sec. Forward and backward movement repetition cycles can be set.					
Wet wiping		Forward movement speed setting: Specified by the machine. Backward movement speed setting: 1 to 225mm/sec. Forward and backward movement repetition cycles can be set.					

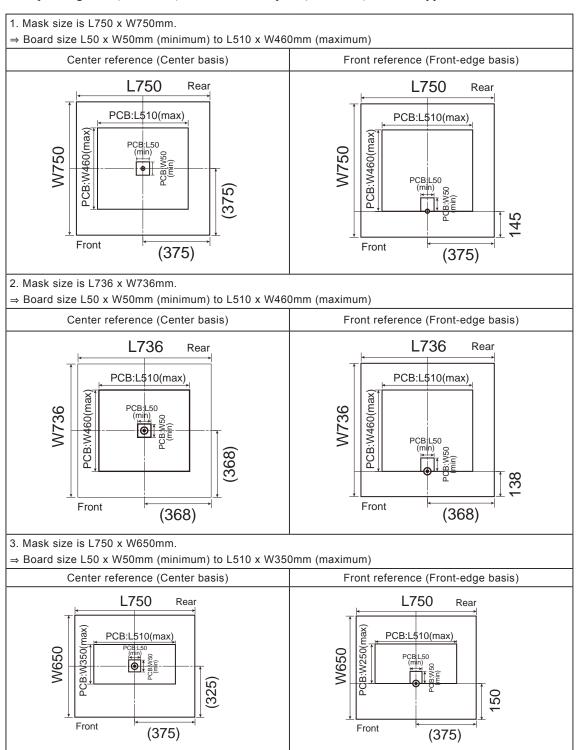
^{*} The board count control and elapsed time control can be set enabled at the same time.

11.5 Applicable board specifications

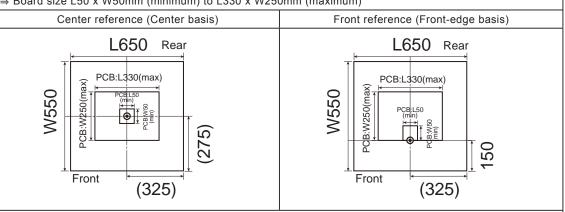
11.5.1 Target board dimensions

Maximum board size: L 510mm x W 460mm Minimum board size: L 50mm x W 50mm

- * The target mask to be combined with the board may vary as shown in the table below.
- * "L" is a direction along the transport direction while "W" is a direction perpendicular to the transport direction.
- * A printing area (L 600mm) or a board transport (L 610mm) can be supported as a custom-order item.

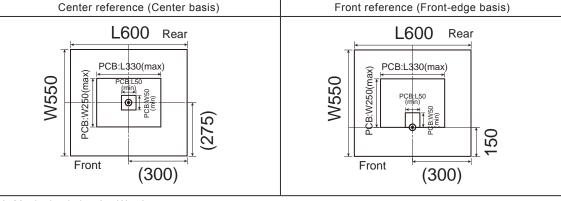


- 4. Mask size is L650 x W550mm.
- ⇒ Board size L50 x W50mm (minimum) to L330 x W250mm (maximum)



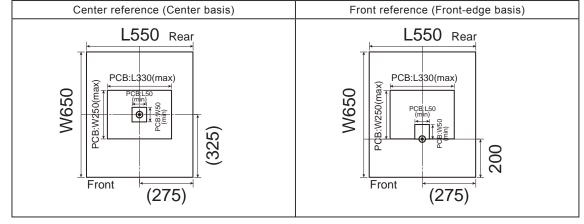
- 5. Mask size is L600 x W550mm.
- ⇒ Board size L50 x W50mm (minimum) to L330 x W250mm (maximum)

For this mask size, [B00071] Mask clamp adapter (left and right paired set) in "1 Machine configuration" is required.



- 6. Mask size is L550 x W550mm.
- ⇒ Board size L50 x W50mm (minimum) to L330 x W250mm (maximum)

For this mask size, [B00071] Mask clamp adapter (left and right paired set) in "1 Machine configuration" is required.

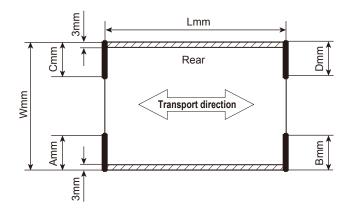


11.5.2 Board specifications

The target board includes non-printable areas as illustrated below. (This non-printable area is used as measures for the printed board inspection operation mode or the transport conditions of the surface mounter that becomes a post-process machine.) Additionally, 8mm-straight zones expressed by "A" to "D" are required to bring the mask in contact with the stopper.

The machine is moved to the "A" to "D" portion according to the board transport direction and conveyor reference of the machine configuration. (Either the front side or rear side of the conveyor transport system of the connected production line machines is set to the fixed reference. The conveyor of the printer also needs to be adjusted to this setting.)

* "L" is a direction along the transport direction while "W" is a direction perpendicular to the transport direction.



Board material : Glass fiber reinforced epoxy resin (For other materials, contact YAMAHA separately.)

Board thickness : 0.4 to 3.0 mm (For boards with a thickness of 1 mm or less, a board pickup clamp

system (including warp prevention system: option) is required.)

Board weight : 1.0 kg/sheet or less (If the board weight exceeds this level, contact YAMAHA separately.)

Board warpage : Upper side ≤ 1.0 mm, Lower side ≤ 0.5 mm

Notch prohibited area : Board transport direction : Right SY → Left, front reference : A=8mm

Board transport direction : Left → Right, front reference : B=8mm

Board transport direction : Right → Left, rear reference : A,C=8mm

Board transport direction : Left → Right, rear reference : B,D=8mm

11.5.3 Restrictions on components on back side of board

In the double-side mounting process or jig transport printing process, there are projections (components or jigs) on the back side of the board before the printing work. The following shows allowable dimensions of such projections.

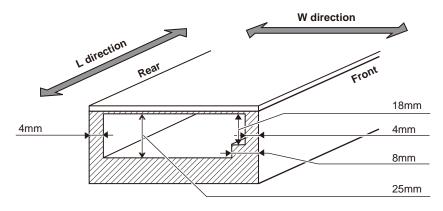
* "L" is a direction along the board transport direction while "W" is a direction perpendicular to the transport direction.

Height from back side of board: 25 mm or less

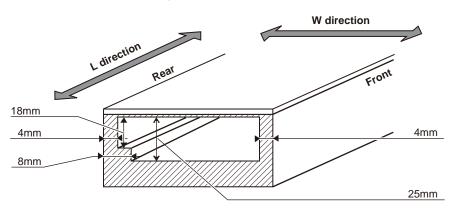
0 mm or less in an area of 4 mm from both ends in the board width directio

18 mm or less in an area of 4 to 8 mm from the conveyor end on the fixed side.

When the front is the conveyor reference:



When the rear is the conveyor reference:



11.5.4 Restrictions on slit board and through hole in board

Slit width: 3 mm or less

Through hole diameter: ϕ 3 mm or less

Sensors (reflection and transmitted light types) are laid out on the conveyor so as to check the position of the

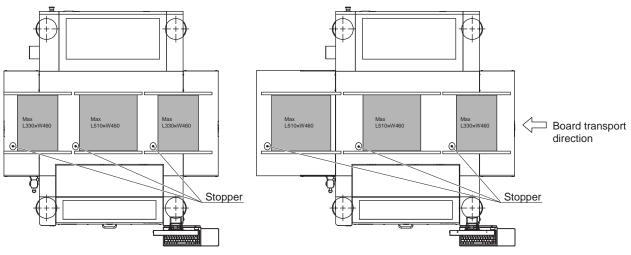
board to be transported.

If the target board has slits or holes, the board cannot be detected correctly.

For such boards, contact YAMAHA separately.

11.5.5 Permissible board dimensions for buffer

Permissible board size for entrance and exit conveyor (standard) buffer: L330mm x W460mm Permissible board size for carry-out side extension conveyor (option) buffer: L510mm x W460mm



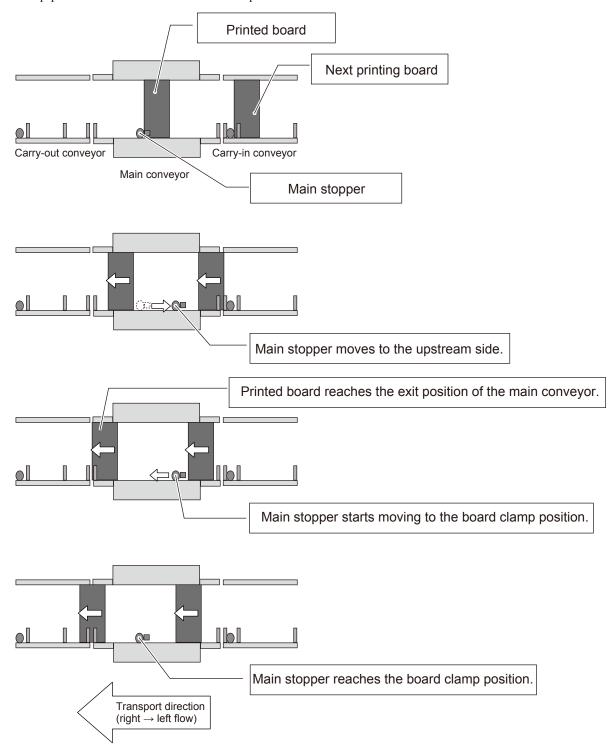
Standard specifications

Carry-out side extension conveyor specifications

11.6 Board transport specifications

In this equipment, the printed board at the print position and the next printing board at the standby position or in the upstream process are transported almost at the same time.

When the printed board at the print position starts unloading and the next printing board at the standby position or in the upstream process starts loading, the main stopper moves to the upstream side of the printed board while it remains moved down. When the main stopper reaches the upstream side of the printed board, it is moved up to physically separate the unloading printed board from the loading next printing board. When the printed board reaches the conveyor exit position sensor, the main stopper moves to the normal board clamp position while it remains moved up.



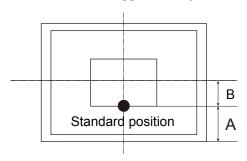
* When the customer manufactures the board backup jig, see "11.8.2 Backup plate (when the customer manufactures the jig)" for further information

11.7 Applicable mask specifications

11.7.1 Mask frame dimensions and mask references

Mask size	Maximum board size (squeegee size)	Mask reference	X-direction		Y-dir	ectio	n		
		Center			Center				
L750×W750	L510×W460 (L530 squeegee)	Center side of machine	Center	А	145	В	230		
		Center		Cen	ter				
L736×W736	L510×W460 (L530 squeegee)	Center side of machine	Center	А	138	В	230		
		Center		Center					
L750×W650	L510×W350 (L530 squeegee)	Center side of machine	Center	А	150	В	175		
		Center		Center					
L650×W550	L330×W250 (L350 squeegee)	Center side of machine	Center	А	150	В	125		
		Center		Center					
L600×W550*	L330×W250 (L350 squeegee)	Center side of machine	Center	А	150	В	125		
		Center		Center					
L550×W650*	L330×W250 (L350 squeegee)	Center side of machine	Center	А	200	В	125		

^{*} These mask sizes are supported only when an optional mask adapter is used.



A: Distance from the outer frame of the mask

B: Distance from the mask center

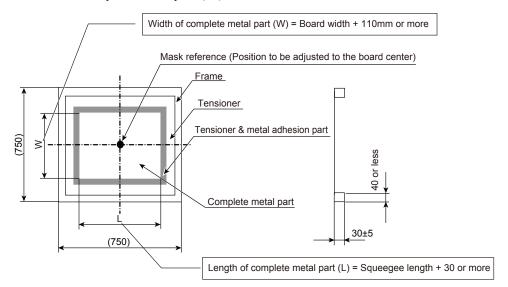
Mask reference: Front

(Standard position: Position where is aligned with the center of the board on the front)

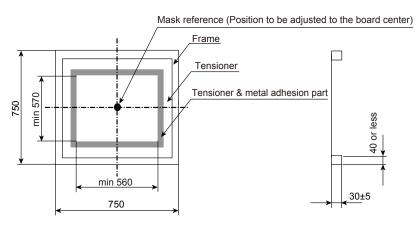
11.7.2 Mask specifications

An appropriate mask maintaining the complete metal part shown below is used according to the target board and squeegee length to be used.

- Length of complete metal part (L) = Squeegee length + 30 mm or more
- Width of complete metal part (W) = Board width + 110 mm or more



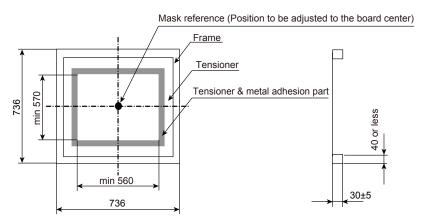
① L750 × W750 center reference (Maximum board size L510 × W460, Squeegee L530)



* Grind the board surface side of the mask frame.

Positional accuracy of mask reference $X,Y \le 2$ mm, R-direction $\pm 0.3^{\circ}$

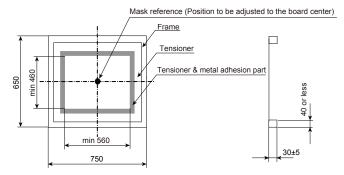
② L736 × W736 center reference (Maximum board size L510 × W460, Squeegee L530)



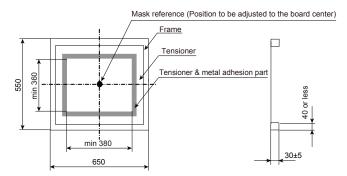
* Grind the board surface side of the mask frame.

Positional accuracy of mask reference $X, Y \le 2 \text{ mm}, \text{ R-direction} \pm 0.3^{\circ}$

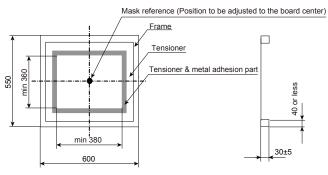
③ L750 × W650 center reference (Maximum board size L510 × W350, Squeegee L530)



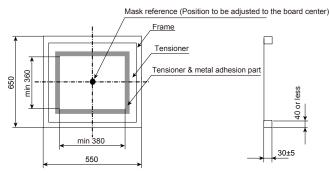
- * Grind the board surface side of the mask frame. Positional accuracy of mask reference $X, Y \le 2$ mm, R-direction $\pm 0.3^{\circ}$
- 4 L650 × W550 center reference (Maximum board size L330 × W250, Squeegee L350)



- * Grind the board surface side of the mask frame. Positional accuracy of mask reference $X, Y \le 2$ mm, R-direction $\pm 0.3^{\circ}$
- ⑤ L600 × W550 center reference (Maximum board size L330 × W250, Squeegee L350)



- * Grind the board surface side of the mask frame. Positional accuracy of mask reference $X, Y \le 2$ mm, R-direction $\pm 0.3^{\circ}$
- ⑥ L550 × W650 center reference (Maximum board size L330 × W250, Squeegee L350)



* Grind the board surface side of the mask frame. Positional accuracy of mask reference $X, Y \le 2 \text{ mm}, R\text{-direction} \pm 0.3^{\circ}$

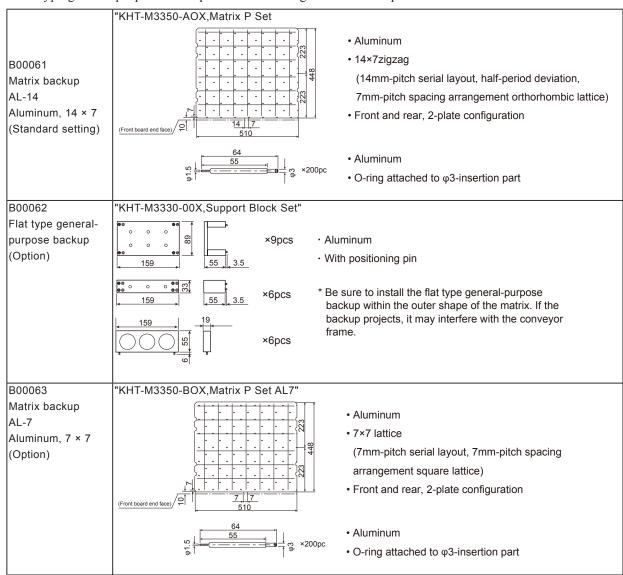
11.8 Board support system

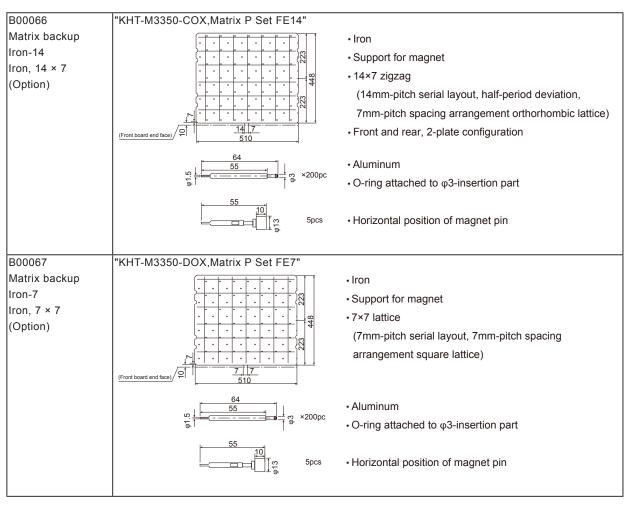
11.8.1 Matrix backup and flat type general-purpose backup

This backup supports the board from the lower portion against the printing pressure, at which the squeegee pushes the board from the upper portion during printing. Five kinds of backups are provided as shown in the table below.

Make desired selections using [B00061 to B00067] Matrix backup XXXXX in "1. Machine configuration".

- * Normally, "AL-14" is used. When necessary, change or add the backup.
 - "Iron-14" and "Iron-7" can use the magnetic force fixed type magnet pin.
 - "Flat type general-purpose backup" does not need any pins. This ensures easy setup work.
 - "Flat type general-purpose backup" can be used together with the pins.

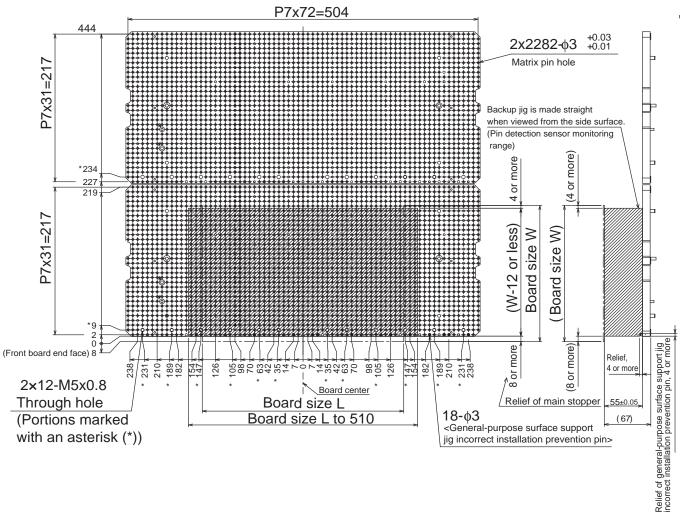




11.8.2 Backup plate (when the customer manufactures the jig)

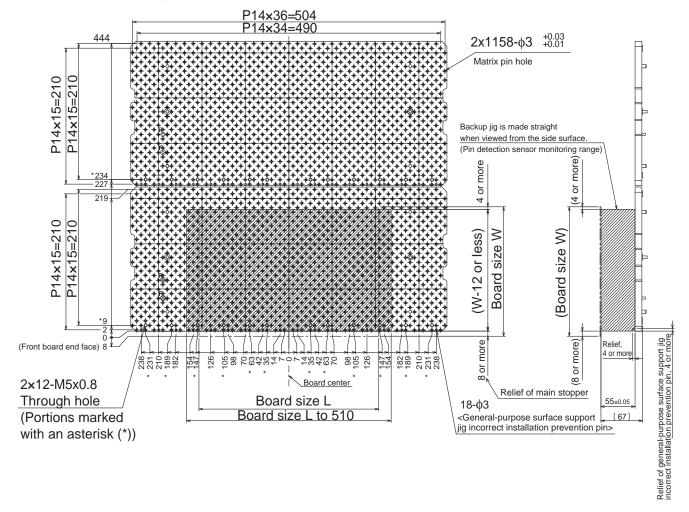
When the customer manufactures the backup jig, make the design while referring to the cautions shown below.

Manufacture specifications of backup jig to be placed on 7×7 lattice matrix plate $< R \Leftrightarrow L$ common high-speed simultaneous transport specifications>



- 1) The backup jig is so designed that it does not protrude the dimensions of the shaded portion shown in this drawing.
- 2) In an area of 8 mm from the front board end, the main stopper moves in the X direction during production.
 - A clearance of 8 mm or more from the board end is put in the Y direction.
 - When the clearance is less than 8 mm, the high-speed simultaneous transport is not performed if the interlock sensor responds.
 - If the interlock sensor does not respond, the high-speed simultaneous transport is performed and the support jig may interfere with the main stopper.
 - For details about manufacture specifications of support jig that makes the interlock sensor respond, consult separately.
- 3) An area of 4 mm from the board end on the rear side is monitored by the pin detection sensor. The backup jig is designed to be straight when viewed from the side surface.
- 4) Ø3-matrix pin hole is used as knock hole for positioning.
- 5) The knock pin uses \emptyset 3h8-pin and its projection dimension is approx. 4 mm. The pitch tolerance of the knock pin hole is ± 0.02 or less.
 - (For the hole dimension tolerance, S7 and P7 are appropriate for aluminum and iron, respectively.)
- 6) General-purpose surface support jig incorrect installation prevention pins are provided at 18 locations on the front of the matrix plate. A relief (depth is 4 mm or more and height is 4 mm or more) is provided at this position on the back side of the jig.

Manufacture specifications of backup jig to be placed on 14×7 zigzag matrix plate $R \Leftrightarrow L$ common high-speed simultaneous transport specifications>



- 1) The backup jig is so designed that it does not protrude the dimensions of the shaded portion shown in this drawing.
- 2) In an area of 8 mm from the front board end, the main stopper moves in the X direction during production.
 - A clearance of 8 mm or more from the board end is put in the Y direction.
 - When the clearance is less than 8 mm, the high-speed simultaneous transport is not performed if the interlock sensor responds.
 - If the interlock sensor does not respond, the high-speed simultaneous transport is performed and the support jig may interfere with the main stopper.
 - For details about manufacture specifications of support jig that makes the interlock sensor respond, consult separately.
- 3) An area of 4 mm from the board end on the rear side is monitored by the pin detection sensor. The backup jig is designed to be straight when viewed from the side surface.
- 4) Ø3-matrix pin hole is used as knock hole for positioning.
- 5) The knock pin uses \emptyset 3h8-pin and its projection dimension is approx. 4 mm. The pitch tolerance of the knock pin hole is ± 0.02 or less.
 - (For the hole dimension tolerance, S7 and P7 are appropriate for aluminum and iron, respectively.)
- 6) General-purpose surface support jig incorrect installation prevention pins are provided at 18 locations on the front of the matrix plate. A relief (depth is 4 mm or more and height is 4 mm or more) is provided at this position on the back side of the jig.

11.9 Signal specifications

11.9.1 Machine-to-machine signal specifications (between this machine and post-process machine)

* NEXT INTERFACE

According to the operating conditions, such as machine combination and signal cable selection, make appropriate selections from the table shown below.

The next interference specifications need to match to the selection of the "11.8.2 Machine-to-machine signal specifications" (between this machine and pre-process machine: Previous interface).

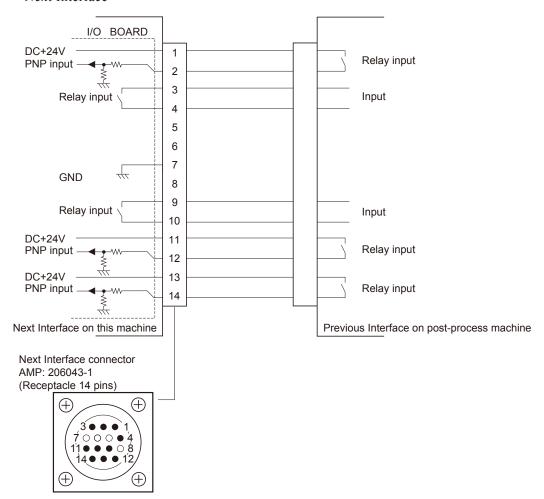
* When connecting to other company's machine, the customer shall be held responsible for maintenance of the functions related to other company's machine.

	Select	ion								
this		IP: 206043-1	GATE sig specificat			ED (extended) ecifications		CED (extended) specifications	SMEMA signal specifications	
(Red	ceptacle 14 p	oins)	YAMAHA YV series or earlier (YV or earlier) and other company's machine		arlier (YV or earlier) and later (X/Xg/YG/YS)		YAMAH or later *1	A YS series (YS)	SMEMA signal compatible machine	
Pin No.	CI	ass	Sig	nal name	Sig	nal name	Si	ignal name	Signal name	
1	DC +24V		GATE IN (com)	Board unloading request signal input from the	BUSY IN (com)	Status signal input showing that the	Same a	s left.		
2	PNP input ON when the +24V.)	(Judged as ne voltage is	GATE IN (input)	post-process machine	BUSY IN (input)	post-process machine is loading the board.				
3	Relay contact output	Conducted/ Closed when	Not used.		BA OUT (output)	Status signal output showing that this	Same a	s left.		
4	Relay contact output	turned ON.			BA OUT (output)					
5	Incorrect connection prevention	Key plug inserted.	Dedicated designation (Blocked)		Dedicated designation (Blocked)		Dedicated to mating designation (Blocked)			
6	function application		Dedicated designation (Receivat		Dedicated designation (Receivate		Dedicated to mating designation (Receivable)			
7	DC 0V	•	Not used.		Not used.		Not use	d.	SMEMA specifications	
8	Reserved.		Reserved	-	Reserved	I_	Reserve	ed.		
9	Relay contact output	Conducted/ Closed when	Not used.		UR OUT (output)	Status signal output showing that this	Same a	s left		
10	Relay contact output	turned ON.	Not used.		UR OUT (output)	machine is running in the automatic operation mode.				
11	DC +24V		Not used.		LR IN (com)	Status signal input showing	Same a	s left		
12	PNP input ON when the +24V.)	(Judged as ne voltage is	Not used.		LR IN (input)	that the post-process machine is running in the automatic operation mode.				
13	DC +24V		Not used.		Not used.		LE IN (com) LE IN (input) Signal input showing the board presence status at the standby position of the post process machine			
14	PNP input ON when the +24V.)	(Judged as ne voltage is	Not used. *2		Not used. *2					

- *1 The YS/YG series mounters have already been applicable to the ADVANCED GATE 2 specifications from the machine shipped in November, 2009. When connecting the YS/YG series mounter shipped before this date to the line, the machine (except for YS24) needs to be modified.
- *2 This signal can be handled as the counter reset signal input. (The signal waits for replacement of the magazine rack of the unloader.)
- [GATE IN]: It is judged that the unloading is requested from the post-process machine when this signal turns ON (conducts). When the work of this machine has been completed, the board is unloaded The post-process machine outputs the relay contact (dry contact: no-voltage circuit).
- [BUSY IN]: This input signal informs this machine that the post-process machine is loading the board. The post-process machine outputs the relay contact (dry contact: no-voltage circuit).
- [BA OUT]: This output signal informs the post-process machine that this machine is ready to unload the board.
- [UR OUT]: This output signal informs the post-process machine that this machine is running in the automatic operation mode.
- [LR IN]: This input signal informs this machine that the post-process machine is running in the automatic operation mode. The post-process machine outputs the relay contact (dry contact: no-voltage circuit).
- [LS IN]: This input signal informs this machine that there is no board at the standby position of the prost-process machine and the post-process machine is ready to receive the board. The post-process machine outputs the relay contact. The cable with the yellow marking put close to the connector is used for the machine-to-machine cable.

Machine-to-machine signal specifications (between this machine and post-process machine)

* Next Interface



11.9.2 Machine-to-machine signal specifications (between this machine and pre-process machine)

* PREVIOUS INTERFACE

According to the operating conditions, such as machine combination and signal cable selection, make appropriate selections from the table shown below.

The previous interference specifications need to match to the selection of the "11.9.1 Machine-to-machine signal specifications" (between this machine and post-process machine: Next interface).

* When connecting to other company's machine, the customer shall be held responsible for maintenance of the functions related to other company's machine.

	Select									
this ı		Connector on MP: 206043-1	GATE sig specificat			ED (extended) ecifications		ED (extended) pecifications	SMEMA signal specifications	
(1100	reptacie, 14	pinoy	YAMAHA YV series or earlier (YV or earlier) and other company's machine		arlier (YV or earlier) nd other company's (X/Xg/YG/YS)				SMEMA signal compatible machine	
Pin No	С	lass	Sig	nal name	Si	gnal name	Si	gnal name	Signal name	
1	Relay contact output Relay	Conducted/ Closed when turned ON.	GATE OUT (output) GATE	Board unloading request signal output to the	BUSY OUT (output) BUSY	Status signal output showing that this machine is	Same as left			
2	contact		OUT (output)	pre-process machine	OUT (output)	loading the board.				
3	DC +24V		Not used.		BA IN (com)	Status signal input showing that the pre-process	Same as	left		
4		(Judged as the voltage	Not used.		BA IN (input)	machine is ready to unload the board.				
5	ncorrect connection			to mating on (Receivable)		d to mating on (Receivable)	Dedicated to mating designation (Receivable)			
6	prevention function application	Key plug inserted.		to mating on (Blocked)		d to mating on (Blocked)	Dedicated to mating designation (Blocked)			
7	Reserved.		Reserved		Reserved	l.	Reserved	l.		
8	Reserved.		Reserved		Reserved	l.	Reserved	l.		
9	DC +24V		Not used.		UR IN (com)	Status signal input showing that the	Same as	left.	SMEMA specifications	
10		(Judged as the voltage	Not used.		UR IN (input)	pre-process machine is running in the automatic operation mode.				
11	Relay contact output	Conducted/ Closed when	Not used.		LR OUT (output)	Status signal output showing that this	Same as left.			
12	Relay contact output	turned ON.	Not used.		LR OUT (output)	machine is running in the automatic operation mode.				
13	Relay contact output	Conducted/ Closed when turned ON.	Not used.		Not used		LE OUT Machine-to- machine board standby signal			
14	Relay contact output	turried Oiv.	Not used.		Not used		LE OUT (output)	output from this machine. (Mounter only)		

*1 The YS/YG series mounters have already been applicable to the ADVANCED GATE 2 specifications from the machine shipped in November, 2009. When connecting the YS/YG series mounter shipped before this date to the line, the machine (except for YS24) needs to be modified.

[GATE OUT]: When this machine is ready for operation, it outputs this board unloading request ON (conduct) signal to the pre-process machine.

[BUSY OUT]: This output signal informs the pre-process machine that this machine is loading the board.

[BA IN]: This input signal informs this machine that the pre-process machine is ready to unload the board. The pre-process machine outputs the relay contact (dry contact: no-voltage circuit).

[UR IN]: This input signal informs this machine that the pre-process machine is running in the automatic operation mode. The pre-process machine outputs the relay contact (dry contact: no-voltage circuit).

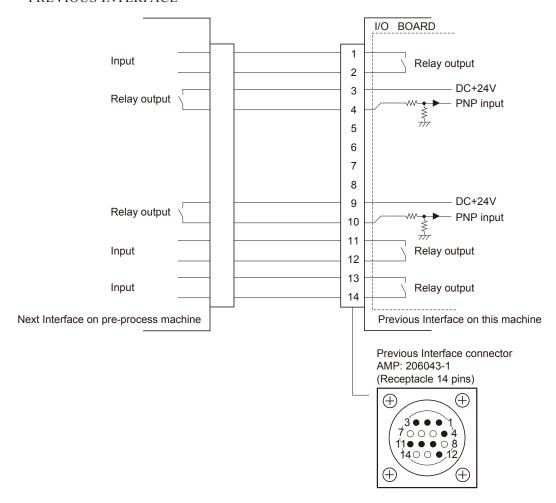
[LR OUT]: This output signal informs the pre-process machine that this machine is running in the automatic operation mode.

[LE OUT]: This signal is used for the ADVANCED (extended) GATE2 specifications. This signal is used when the machine-to-machine board standby function that is used between the mounters is set enabled.

This output signal informs the pre-process machine that the board between this machine and pre-process machine is in the standby status. The cable with the yellow marking put close to the connector is used for the machine-to-machine cable.

Machine-to-machine signal specifications (between this machine and pre-process machine)

* PREVIOUS INTERFACE



11.10 Safety design

This equipment conforms to the EU Machinery Directive 2006/42/EC (*1) and EMC Directive 2004/108/EC (CE marking).

However, this equipment does not bear CE marking if a custom-order item (with the special specifications) was installed.

For details, see "10.5 CE marking".

Emergency stop system and error detection system

To ensure the safety, emergency stop system and error detection system shown in the table below are provided.

No.	System area and item	Registration name	Built-in	Remarks
01	Emergency stop on front operation console	SB31	0	Push-lock and turn-reset switch
02	Emergency stop on rear operation console	SB32	0	Push-lock and turn-reset switch
03	Emergency stop on Carry-out side extension conveyor (*1)	SB33	Δ	Push-lock and turn-reset switch
04	Emergency stop on Carry-out side extension conveyor (*2)	SB34	Δ	Push-lock and turn-reset switch
05	Upper safety cover on front	SQ050	0	Mechanical switch with key
06	Lower safety cover on front	SQ051	0	Mechanical switch with key
07	Safety cover on rear	SQ052	0	Mechanical switch with key
08	Safety cover of carry-out side extension conveyor (*1)	SQ054	Δ	Mechanical switch with key
09	Safety cover of carry-out side extension conveyor (*2)	SQ055	Δ	Mechanical switch with key
10	Servo 1 group of servo control box	SRV1	0	Y/Z/MS-axis error detection
11	Servo 2 group of servo control box	SRV2	0	PU/SY/W1/W2-axis error detection
12	Servo 3 group of servo control box	SRV3	0	X1/X2/FX/FP-axis error detection
13	Servo 4 group of servo control box	SRV4	0	SZ/CX/W3/SR-axis error detection
14	Board table Y	SQ021	0	Y-axis over-travel detection
15	Board camera (& inspection camera)	SQ002	0	Camera axis over-travel detection

- * Meaning of "Built-in" mark ==> ② : Provided. X: None △ : Option selection
- * "Registration name" is described in the control wiring diagram for the maintenance support (Y-DO Web
- * (*1) These items are used when the carry-out side extension conveyor (option) is installed on the right. The items become invalid when the board transport direction is right \rightarrow left flow. The items (*1) and (*2) are set exclusively.
- * (*2) These items are used when the carry-out side extension conveyor (option) is installed on the left. The items become invalid when the board transport direction is left \rightarrow right flow. The items (*1) and (*2) are set exclusively.
- In addition to these items, temperature error, fan stop, and power supply error are provided as hardware related error detection items.
 - For details, see the user's manuals.

11.10.2 Pause (interlock) system and error detection system

To protect the machine or continue the operation, pause system and error detection system shown in the table below are provided.

No.	System area and item	Registration name	Built-in	Remarks
01	Board table Y	SQ022	0	Front interference detection
02	Board table Y	SQ023	0	Rear interference detection
03	Board table X1	SQ032	0	Confirmation of X1-axis movement safety area
04	Board table X2	SQ033	0	Confirmation of X2-axis movement safety area
05	Board table Z	SQ219	0	Confirmation of Z-axis movement safety area
06	Squeegee (*1)	SQ359	0	Confirmation of squeegee back/forth movement safety area
07	Squeegee (*1)	SQ111	0	Confirmation of squeegee swing rotation safety area
08	PSC unit	SQ353	Δ	Confirmation of solder paste supply left/right movement safety area
09	Main stopper and mask camera	SQ211	0	Detection of interference in left/right movement area
10	Board push-up	SQ212	0	Detection of pin/block interference
11	Automatic cleaning system	VACGD	0	Confirmation of vacuum suction force
12	Suction blower/inverter	AL0AL1	0	Error detection
13	Air-conditioner	ACAL	Δ	Error detection
14	Supply air pressure	AIRPR	0	Air pressure drop

- * Meaning of "Built-in" mark ===> ◎: Provided.
- × : None
- \triangle : Option selection
- * "Registration name" is described in the control wiring diagram for the maintenance support (Y-DO Web site).
- * (*1) This is used when the 3S head is installed and disabled when the double squeegee head is installed.
- * In addition to these items, XY-axis soft limit setting and board transport error are provided as software error detection items.
 - For details, see the user's manuals.

11.10.3 Configuration of servo control axes

According to the total number of axes and machine configuration, 13 to 15 axes are controlled by the AC servo motors.

No.	Area and item	Control axis name	Motor name	Built- in	Remarks
01	Board table Y	Υ	M01	0	
02	Board table X1	X1	M02	0	
03	Board table X2	X2	M03	0	
04	Board table Z	Z	M04	0	Electromagnetic brake is built-in.
05	Push-up	PU	M05	0	Electromagnetic brake is built-in.
06	Main stopper and mask camera	MS	M06	0	
07	Entrance conveyor width	W1	M07	0	
08	Board table conveyor width	W2	M08	0	Electromagnetic brake is built-in.
09	Exit conveyor width	W3	M09	0	
10	Squeegee back/forth	SY	M10	0	Electromagnetic brake is built-in.
11	Board camera (& inspection camera)	СХ	M11	0	
12	Squeegee up/down	SZ	M12	0	Electromagnetic brake is built-in.
13	Squeegee swing rotation (*1)	SR	M13	0	Electromagnetic brake is built-in.
14	PSC pot holder up/down (*2)	FP	M18	Δ	
15	PSC left/right movement	FX	M19	Δ	
	Total number of axes				13 to 15

^{*} Meaning of "Built-in" mark ===> ◎: Provided.

11.10.4 Configuration of general-purpose motor

Total number of motors, 4 motors

No.	Area and item	Motor name	Built- in	Remarks
01	Entrance conveyor	M14	0	Variable speed brushless DC motor
02	Board table conveyor	M15	0	Variable speed brushless DC motor
03	Exit conveyor	M16	0	Variable speed brushless DC motor
04	Suction blower (Automatic cleaning system)	M17	0	
	Total number of axes	4		

^{*} Meaning of "Built-in" mark ===> ② : Provided.

11.10.5 Configuration of other motors

To cool the control box, motors, and cameras, FAN motors are installed at appropriate positions.

X: None

 $[\]triangle$: Option selection

^{* &}quot;Motor name" is described in the control wiring diagram for the maintenance support (Y-DO Web site).

^{* (*1)} This is disabled when the double squeegee head is installed.

^{* (*2)} This is disabled when the syringe type PSC is installed.

^{×:} None

 $[\]triangle$: Option selection

^{* &}quot;Motor name" is described in the control wiring diagram for the maintenance support (Y-DO Web site).